SLLS095D - SEPTEMBER 1973 - REVISED OCTOBER 1998

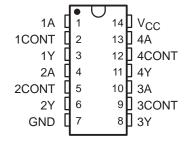
- Input Resistance . . . 3 k Ω to 7 k Ω
- Input Signal Range . . . ±30 V
- Operate From Single 5-V Supply
- Built-In Input Hysteresis (Double Thresholds)
- Response Control that Provides: Input Threshold Shifting Input Noise Filtering
- Meet or Exceed the Requirements of TIA/EIA-232-F and ITU Recommendation V.28
- Fully Interchangeable With Motorola™ MC1489 and MC1489A

description

These devices are monolithic low-power Schottky quadruple line receivers designed to satisfy the requirements of the standard interface between data-terminal equipment and data-communication equipment as defined by TIA/EIA-232-F. A separate response-control (CONT) terminal is provided for each receiver. A resistor or a resistor and bias-voltage source can be connected between this terminal and ground to shift the input threshold levels. An external capacitor can be connected between this terminal and ground to provide input noise filtering.

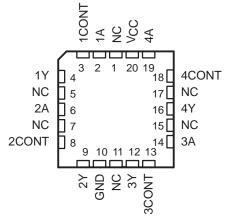
The SN55189 and SN55189A are characterized for operation over the full military temperature range of -55°C to 125°C. The MC1489, MC1489A, SN75189, and SN75189A are characterized for operation from 0°C to 70°C.

SN55189, SN55189A . . . J OR W PACKAGE MC1489, MC1489A, SN75189, SN75189A D, N, OR NS[†] PACKAGE (TOP VIEW)



† The NS package is only available left-end taped and reeled. For SN75189, order SN75189NSR.

SN55189, SN55189A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

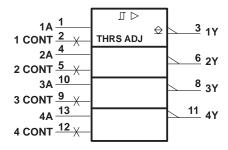


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Motorola is a trademark of Motorola, Incorporated.

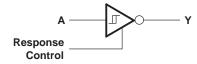


logic symbol†

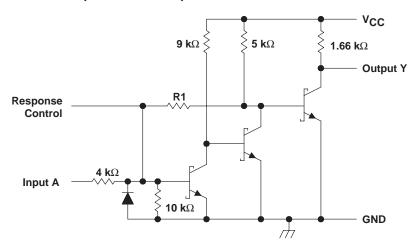


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, NS, and W packages.

logic diagram (positive logic)



schematic (each receiver)



| | MC1489 SN55189 SN75189 | MC1489A SN55189A SN75189A |
|----|------------------------------|---------------------------------|
| R1 | 8.4 kΩ | 1.84 kΩ |

Resistor values shown are nominal.

MC1489, MC1489A, SN55189, SN55189A, SN75189, SN75189A QUADRUPLE LINE RECEIVERS

SLLS095D - SEPTEMBER 1973 - REVISED OCTOBER 1998

NOTES: 1. All voltage values are with respect to the network ground terminal.

DISSIPATION RATING TABLE

| PACKAGE | $T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING | DERATING FACTOR ABOVE T _A = 25°C | T _A = 70°C POWER RATING | T _A = 125°C POWER RATING |
|---------|--|--|---------------------------------------|--|
| D | 950 mW | 7.6 mW/°C | 608 mW | N/A |
| FK | 1375 mW | 11.0 mW/°C | 880 mW | 275 mW |
| J‡ | 1375 mW | 11.0 mW/°C | 880 mW | 275 mW |
| N | 1150 mW | 9.2 mW/°C | 736 mW | N/A |
| NS | 625 mW | 4.0 mW/°C | 445 mW | N/A |
| W | 1000 mW | 8.0 mW/°C | 640 mW | 200 mW |

[‡] In the J package, SN55189 and SN55189A chips are either silver glass or alloy mounted.

recommended operating conditions

| | MIN | NOM | MAX | UNIT |
|--|-----|-----|------|------|
| Supply voltage, V _{CC} | 4.5 | 5 | 5.5 | V |
| Input voltage, V _I | -25 | | 25 | V |
| High-level output current, IOH | | | -0.5 | mA |
| Low-level output current, IOL | | | 10 | mA |
| Operating free-air temperature, T _A | 0 | | 70 | °C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

MC1489, MC1489A, SN55189, SN55189A, SN75189, SN75189A QUADRUPLE LINE RECEIVERS

SLLS095D - SEPTEMBER 1973 - REVISED OCTOBER 1998

electrical characteristics over operating free-air temperature range, V_{CC} = 5 V \pm 1% (unless otherwise noted)

| | PARAMETER | TEST FIGURE | TEST | | SN55189 N55189 <i>F</i> | | MC14 | UNIT | | | | |
|------------------|--|----------------|-------------------------|---|----------------------------|-----|------|-------|-----|------|----------|--|
| | | | | MIN | TYP‡ | MAX | MIN | TYP‡ | MAX | | | |
| | | | | T _A = 25°C | 1 | 1.3 | 1.5 | 1 | 1.3 | 1.5 | | |
| | Positive-going input | | '89 | $T_A = 0$ °C to 70 °C | | | | 0.9 | | 1.6 | | |
| V _{IT+} | | 1 | | $T_A = -55^{\circ}C \text{ to } 125^{\circ}C$ | 0.6 | | 1.9 | | | | V | |
| *11+ | threshold voltage | ' | | T _A = 25°C | 1.75 | 1.9 | 2.25 | 1.75 | 1.9 | 2.25 | • | |
| | | | '89A | $T_A = 0$ °C to 70 °C | | | | 1.55 | | 2.25 | | |
| | | | | $T_A = -55^{\circ}C$ to $125^{\circ}C$ | 1.30 | | 2.65 | | | | | |
| | Negative-going input threshold voltage | | | T _A = 25°C | 0.75 | 1.0 | 1.25 | 0.75 | 1.0 | 1.25 | | |
| $V_{\text{IT}-}$ | | 1 | '89, '89A | $T_A = 0$ °C to 70 °C | | | | 0.65 | | 1.25 | V | |
| | | | | $T_A = -55^{\circ}C$ to $125^{\circ}C$ | 0.35 | | 1.6 | | | | | |
| Vон | High-level | 1 | $V_I = 0.75 V$, | $I_{OH} = -0.5 \text{ mA}$ | 2.6 | 4 | 5 | 2.6 | 4 | 5 | V | |
| VOH | output voltage | ' | Input open, | $I_{OH} = -0.5 \text{ mA}$ | 2.6 | 4 | 5 | 2.6 | 4 | 5 | V | |
| VOL | Low-level output voltage | 1 | V _I = 3 V, | I _{OL} = 10 mA | | 0.2 | 0.45 | | 0.2 | 0.45 | V | |
| | High-level | 2 | V _I = 25 V | | 3.6 | | 8.3 | 3.6 | | 8.3 | mA | |
| ΊΗ | input current | 2 | V _I = 3 V | | 0.43 | | | 0.43 | | | IIIA | |
| i | Low-level | 2 | $V_{I} = -25 \text{ V}$ | | -3.6 | | -8.3 | -3.6 | | -8.3 | mA | |
| ۱۱۲ | input current | | V _I = −3 V | | -0.43 | | | -0.43 | | | IIIA | |
| los | Short-circuit output current | 3 | | | | -3 | | | -3 | | mA | |
| ICC | Supply current | 2 | V _I = 5 V, | Outputs open | | 20 | 26 | | 20 | 26 | mA | |

[†] All characteristics are measured with the response-control terminal open.

switching characteristics, V_{CC} = 5 V, C_L = 15 pF, T_A = 25°C

| | PARAMETER | TEST FIGURE | TEST CONDITIONS | MIN | TYP | MAX | UNIT | |
|------|---|----------------|-----------------------------|-----|-----|-----|-------|--|
| tPLH | Propagation delay time, low- to high-level output | | $R_L = 3.9 \text{ k}\Omega$ | | 25 | 85 | no | |
| tPHL | Propagation delay time, high- to low-level output | 4 | $R_L = 390 \Omega$ | | 25 | 50 | ns | |
| tTLH | Transition time, low- to high-level output | 4 | $R_L = 3.9 \text{ k}\Omega$ | | 120 | 175 | | |
| tTHL | Transition time, high- to low-level output | | $R_L = 390 \Omega$ | | 10 | 20 | 20 ns | |

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION[†]

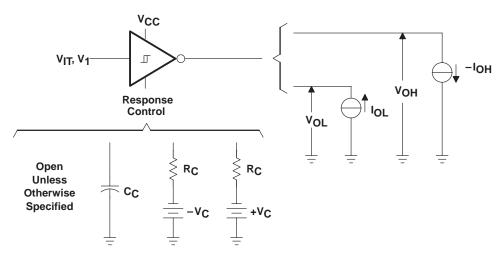
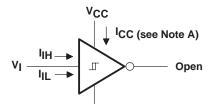


Figure 1. V_{IT+} , V_{IT-} , V_{OH} , V_{OL}



Response Control Open

NOTE A: I_{CC} is tested for all four receivers simultaneously.

Figure 2. I_{IH} , I_{IL} , I_{CC}

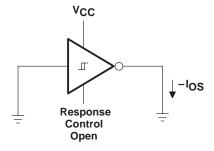
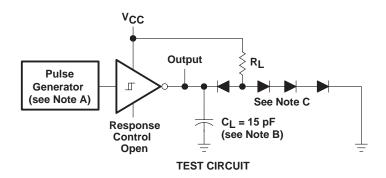
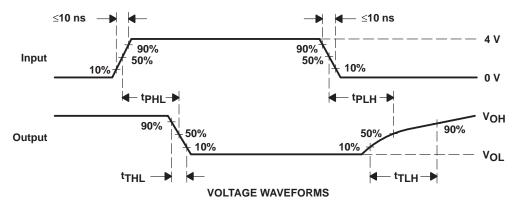


Figure 3. Ios

[†] Arrows indicate actual direction of current flow. Current into a terminal is a positive value.

PARAMETER MEASUREMENT INFORMATION





NOTES: A. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, $t_W = 500 \text{ ns}$.

- B. C_L includes probe and jig capacitances.
- C. All diodes are 1N3064 or equivalent.

Figure 4. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

SN65189, SN75189 OUTPUT VOLTAGE vs

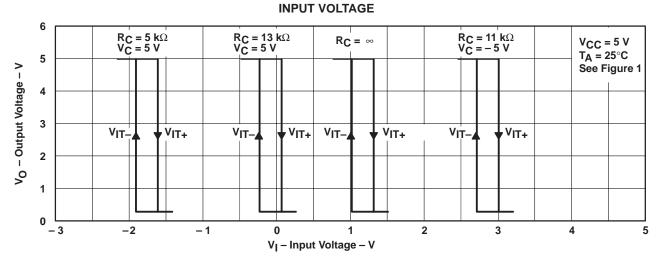


Figure 5

SN65189A, SN75189A OUTPUT VOLTAGE

INPUT VOLTAGE

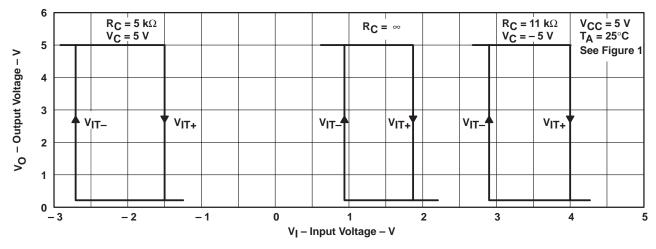


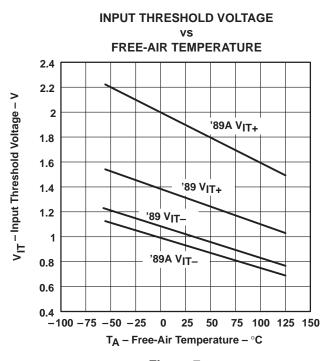
Figure 6

TYPICAL CHARACTERISTICS[†]

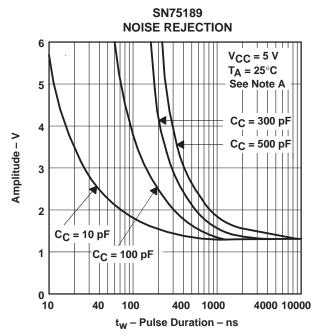
0.2

2

3







NOTE A: Maximum amplitude of a positive-going pulse that, starting from 0 V, will not cause a change in the output level.

SUPPLY VOLTAGE

2
1.8
789A VIT+
789 VIT789 VIT789 VIT789 VIT789 VIT789 VIT789 VIT789 VIT789 VIT-

INPUT THRESHOLD VOLTAGE

Figure 8

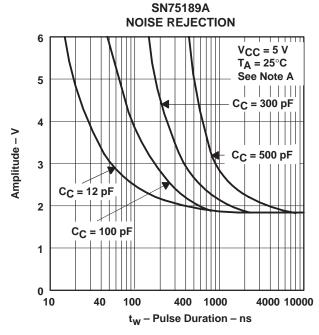
6

V_{CC} - Supply Voltage - V

8

9

10



NOTE A: Maximum amplitude of a positive-going pulse that, starting from 0 V, will not cause a change in the output level.

Figure 9 Figure 10

[†] Data for free-air temperatures below 0°C and above 70°C are applicable to SN55189 and SN55189A circuits only.



TYPICAL CHARACTERISTICS

INPUT CURRENT vs **INPUT VOLTAGE** 10 $V_{CC} = 5 V$ 8 **Control Open** $T_A = 25^{\circ}C$ 6 I_I - Input Current - mA 2 0 -2 -4 -6 -8 -10 5 10 -25 -20 -15 -10 -5 0 15 20

Figure 11

V_I - Input Voltage - V





10-Jun-2014

PACKAGING INFORMATION

| Orderable Device | Status | Package Type | _ | Pins | _ | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking | Samples |
|------------------|----------|--------------|---------|------|------|----------------------------|------------------|--------------------|--------------|---------------------------------------|---------|
| | (1) | | Drawing | | Qty | (2) | (6) | (3) | | (4/5) | |
| 5962-86888022A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962- 86888022A SNJ55 189AFK | Samples |
| 5962-8688802CA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-8688802CA SNJ55189AJ | Samples |
| 5962-8688802DA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-8688802DA SNJ55189AW | Samples |
| MC1489AN | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | MC1489AN | Samples |
| MC1489ANE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | MC1489AN | Samples |
| MC1489N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | MC1489N | Samples |
| MC1489NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | MC1489N | Samples |
| SN55189AJ | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SN55189AJ | Samples |
| SN55189J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI | -55 to 125 | | |
| SN75189AD | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189A | Samples |
| SN75189ADE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189A | Samples |
| SN75189ADR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189A | Samples |
| SN75189ADRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189A | Samples |
| SN75189AN | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN75189AN | Samples |
| SN75189ANE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN75189AN | Samples |
| SN75189ANSLE | OBSOLETE | ≣ SO | NS | 14 | | TBD | Call TI | Call TI | 0 to 70 | | |
| SN75189ANSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189A | Samples |





www.ti.com 10-Jun-2014

| Orderable Device | Status | Package Type | Package Drawing | Pins | Package Qty | Eco Plan | Lead/Ball Finish (6) | MSL Peak Temp | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|----------|--------------|--------------------|------|----------------|----------------------------|----------------------|--------------------|--------------|---------------------------------------|---------|
| SN75189ANSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189A | Samples |
| SN75189D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189 | Sample |
| SN75189DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189 | Sample |
| SN75189DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189 | Sample |
| SN75189N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN75189N | Sample |
| SN75189NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | 0 to 70 | SN75189N | Sample |
| SN75189NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | 0 to 70 | SN75189 | Sample |
| SNJ55189AFK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 5962- 86888022A SNJ55 189AFK | Sample |
| SNJ55189AJ | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-8688802CA SNJ55189AJ | Sample |
| SNJ55189AW | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 5962-8688802DA SNJ55189AW | Sample |
| SNJ55189FK | OBSOLETE | LCCC | FK | 20 | | TBD | Call TI | Call TI | -55 to 125 | | |
| SNJ55189J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI | -55 to 125 | | |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.





10-Jun-2014

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN55189, SN55189A, SN75189, SN75189A:

Catalog: SN75189, SN75189A

Military: SN55189, SN55189A

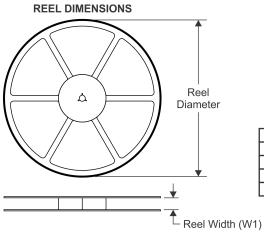
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| Α0 | Dimension designed to accommodate the component width |
|----|---|
| | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| All differsions are nominal | ii difficitorio die fiorificial | | | | | | | | | | | |
|-----------------------------|---------------------------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
| SN75189ADR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN75189ADR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN75189DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN75189NSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |

www.ti.com 8-Apr-2013



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN75189ADR | SOIC | D | 14 | 2500 | 333.2 | 345.9 | 28.6 |
| SN75189ADR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN75189DR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN75189NSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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